

INTEGRATED CIRCUIT DEVICE PACKAGE HAVING A SUPPORT COATING FOR IM- PROVED RELIABILITY DURING TEMPERA- TURE CYCLING

Abstract

An apparatus and method for increasing integrated circuit device package reliability is disclosed. According to one embodiment of the present invention, a support coating is added to a wafer after solder bumps have been added but prior to dicing. This support coating or underfill layer provides added strength to the eventual reflowed solder connections, such that the operational lifetime of these connections is increased with respect to failure due to temperature cycling.